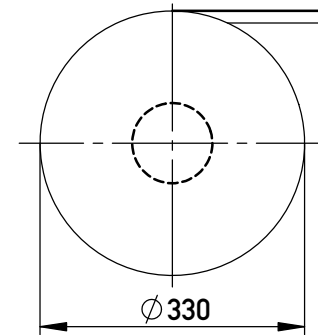
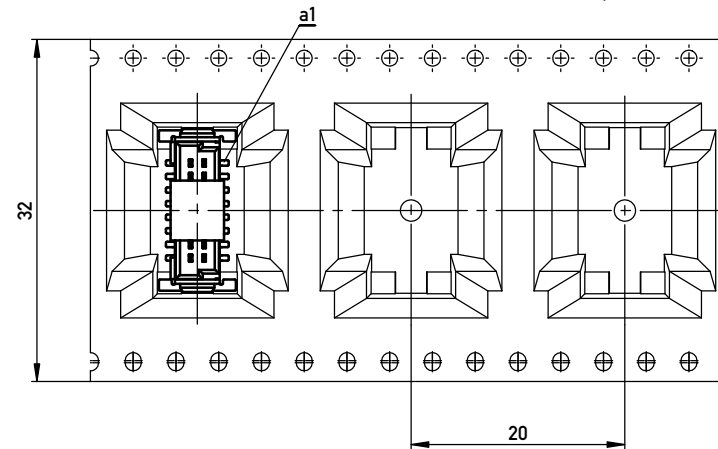


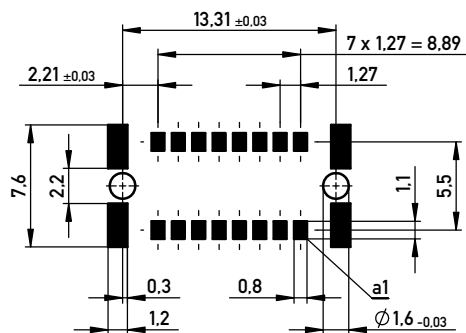
Verpackt in Gurtverpackung
 Tape on Reel Packaging
 Verpackungseinheit: 250 Stück
 Packaging unit: 250 pcs



Abspulrichtung - Reel off Direction



Leiterplatten-Layout Vorschlag für SMT
 PCB-Layout Proposal for SMT



Anforderungsstufe 1
 Performance Level 1

Kontaktbereich vergoldet
 Mating Area gold plating

Anschlussbereich verzinkt 4-6 µm
 Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
 Coplanarity Area of Termination ≤ 0,1 mm

BA 8-23 - hohe Bauhöhe
 type 8-23 - High Profile

Information:	Tolerances	 All Dimensions in mm	Scale	3:1
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Subject to modification without prior notice. Drawing will not be updated.		www.ERNI.com		254414
d	17.07.2013	Class		SMCQ
Index	Date			A3

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